

RESPONSE TO OFFICE ACTION
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IN THE SPECIFICATION:

Please amend the abstract was indicated:

[0082] A semiconductor wafer support assembly and method of fabricating the same are provided. In one embodiment, the method and resulting assembly include attaching a pedestal joining-ring to a bottom surface of a ceramic puck. Low temperature brazing a composite cooling plate structure to the bottom surface of the ceramic puck, where the pedestal joining-ring circumscribes the composite cooling plate structure. Thereafter, a pedestal is electron-beam welded to the pedestal joining-ring. In a second embodiment, ~~for a full area temperature controlled assembly, a method and assembly include a ceramic puck having a wafer support surface, and a composite cooling plate structure having a diameter at least equal to the wafer support surface. A pedestal joining ring is attached to a bottom surface of the composite cooling plate structure. A bottom surface of the ceramic puck is low temperature brazed to the composite cooling plate structure, and then a pedestal is electron beam welded to the pedestal joining ring. In a third embodiment, for a full area temperature controlled semiconductor wafer support assembly, a method and assembly include a ceramic puck having a wafer support surface, and an aluminum containing composite cooling plate structure having a diameter at least equal to the wafer support surface. A pedestal joining ring is low temperature brazed to a bottom surface of the composite cooling plate structure. A bottom surface of the ceramic puck is low temperature brazed to the composite cooling plate structure. Then a pedestal is electron beam welded to the pedestal joining ring.~~